



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

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## DRC5115G0L

Silicon NPN epitaxial planar type

For digital circuits

Complementary to DRA5115G

DRC2115G in SMini3 type package

### ■ Features

- Low collector-emitter saturation voltage  $V_{ce(sat)}$
- Halogen-free / RoHS compliant  
(EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

### ■ Marking Symbol: NX

### ■ Packaging

Embossed type (Thermo-compression sealing) : 3 000 pcs / reel (standard)

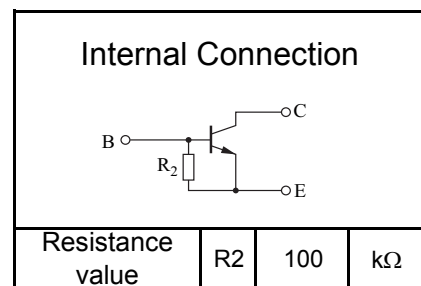
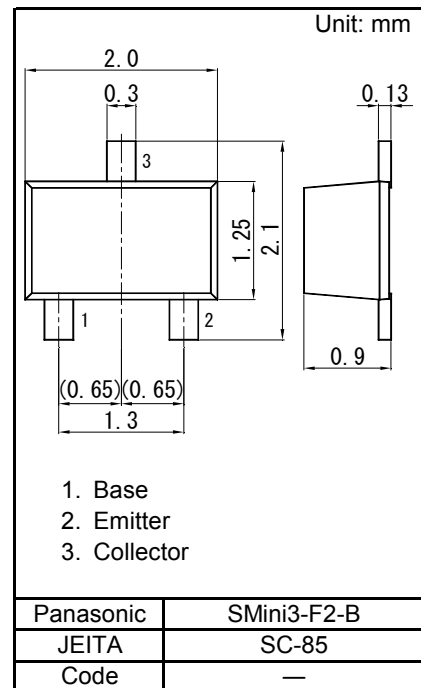
### ■ Absolute Maximum Ratings $T_a = 25\text{ }^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	VCBO	50	V
Collector-emitter voltage (Base open)	VCEO	50	V
Collector current	IC	100	mA
Total power dissipation	PT	150	mW
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

### ■ Electrical Characteristics $T_a = 25\text{ }^\circ\text{C} \pm 3\text{ }^\circ\text{C}$

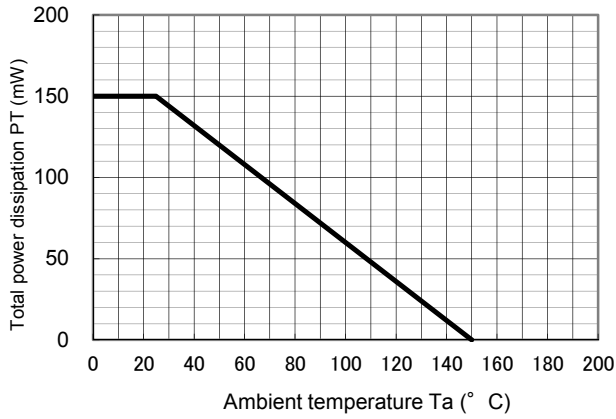
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	VCBO	IC = 10 $\mu$ A, IE = 0	50			V
Collector-emitter voltage (Base open)	VCEO	IC = 2 mA, IB = 0	50			V
Collector-base cutoff current (Emitter open)	ICBO	VCB = 50 V, IE = 0			0.1	$\mu$ A
Collector-emitter cutoff current (Base open)	ICEO	VCE = 50 V, IB = 0			0.5	$\mu$ A
Emitter-base cutoff current (Collector open)	IEBO	VEB = 6 V, IC = 0			0.1	mA
Forward current transfer ratio	hFE	VCE = 10 V, IC = 5 mA	80			-
Collector-emitter saturation voltage	VCE(sat)	IC = 10 mA, IB = 0.5 mA			0.25	V
Input voltage	Vi(on)	VCE = 0.2 V, IC = 5 mA	0.9			V
	Vi(off)	VCE = 5 V, IC = 100 $\mu$ A			0.4	V
Between emitter base resistance	R2		-30%	100	+30%	k $\Omega$

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

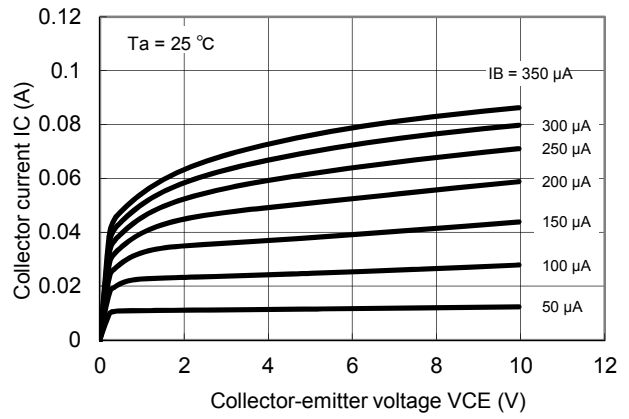


Technical Data ( reference )

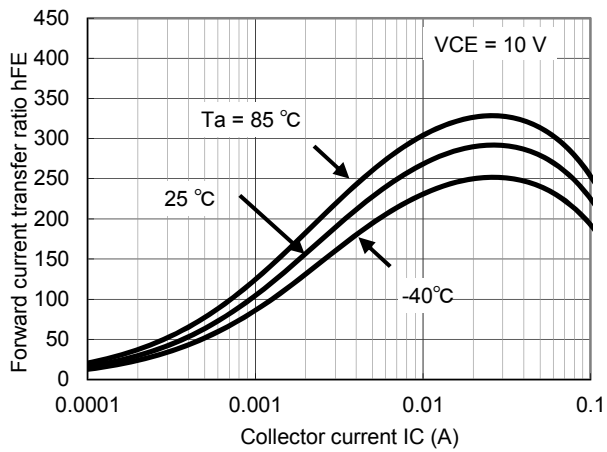
PT - Ta



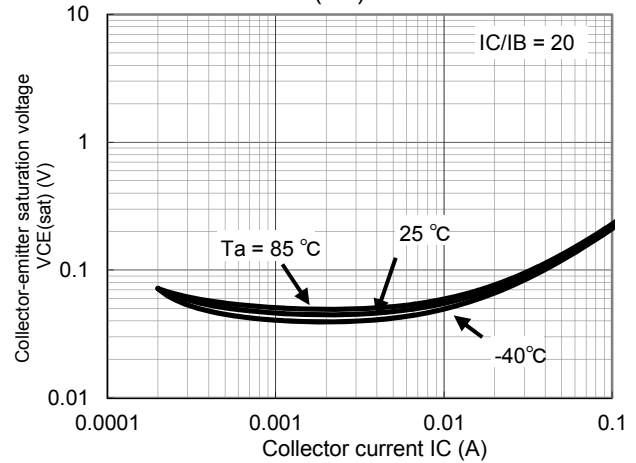
IC - VCE



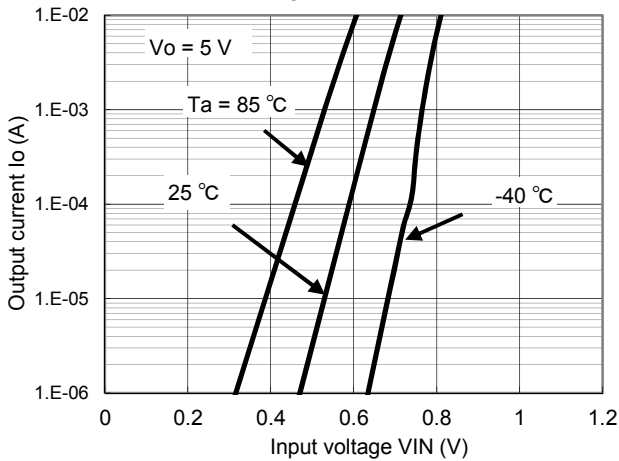
hFE - IC



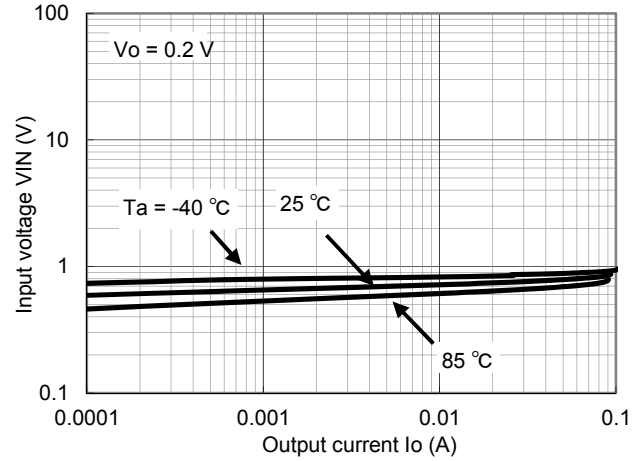
VCE(sat) - IC



Io - VIN



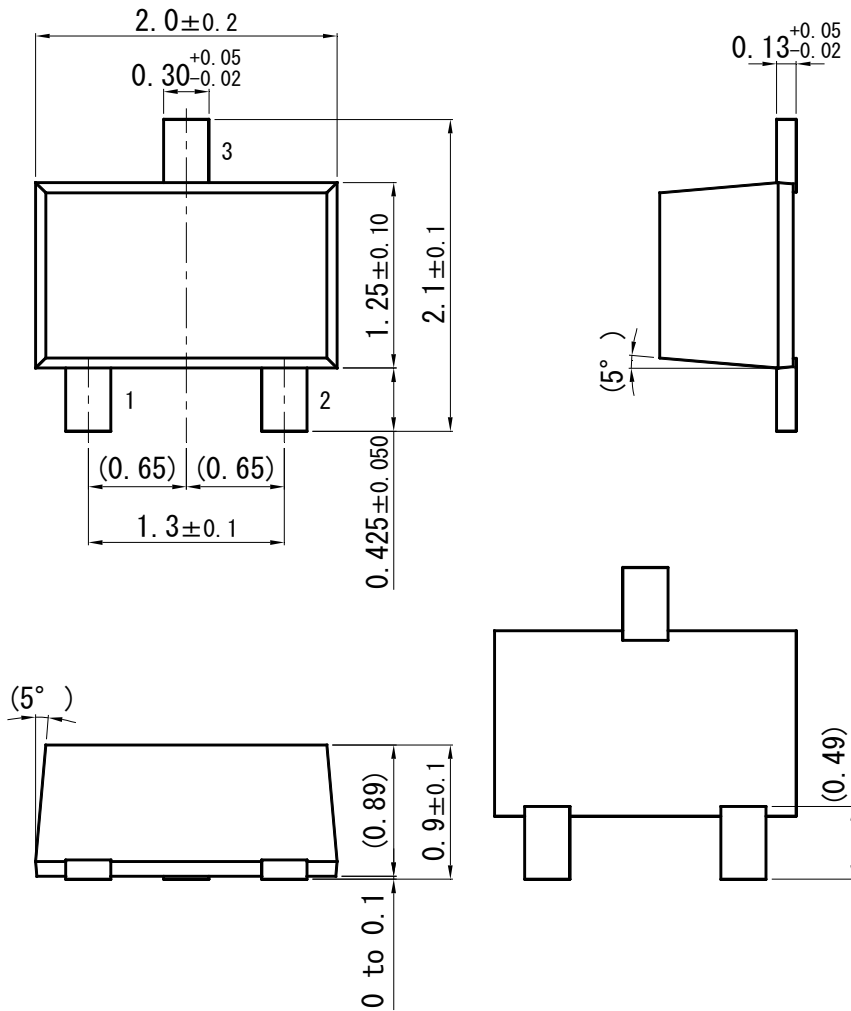
VIN - Io



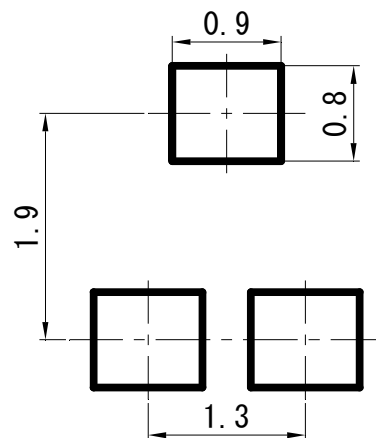


### SMini3-F2-B

Unit: mm



#### ■ Land Pattern (Reference) (Unit: mm)





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